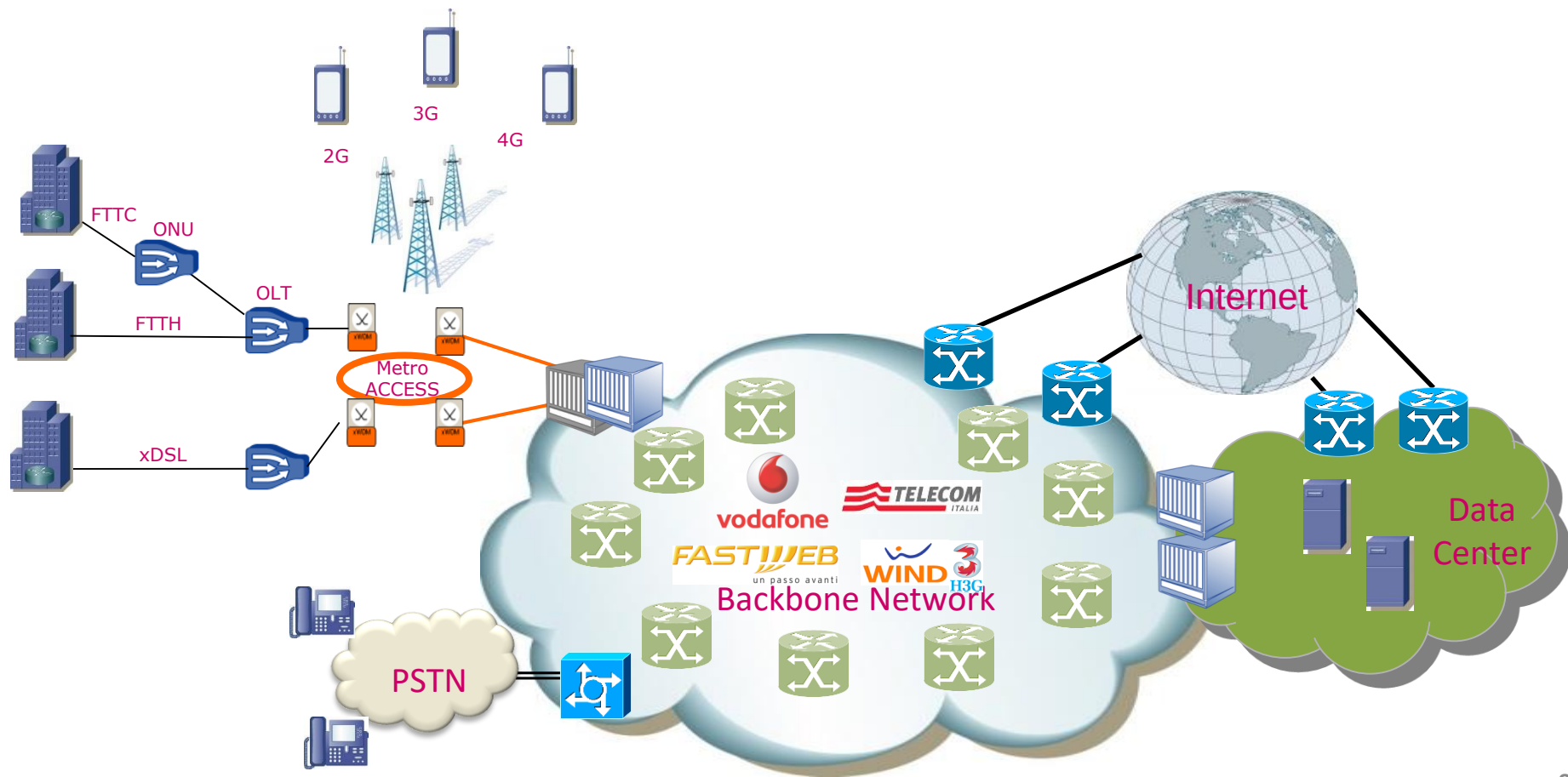


State of the art Routers Architecture (Juniper, Cisco, Huawei)

Relatore: Ing. Nicola Zambelli (K Labs Trainer and Professional Services Engineer)

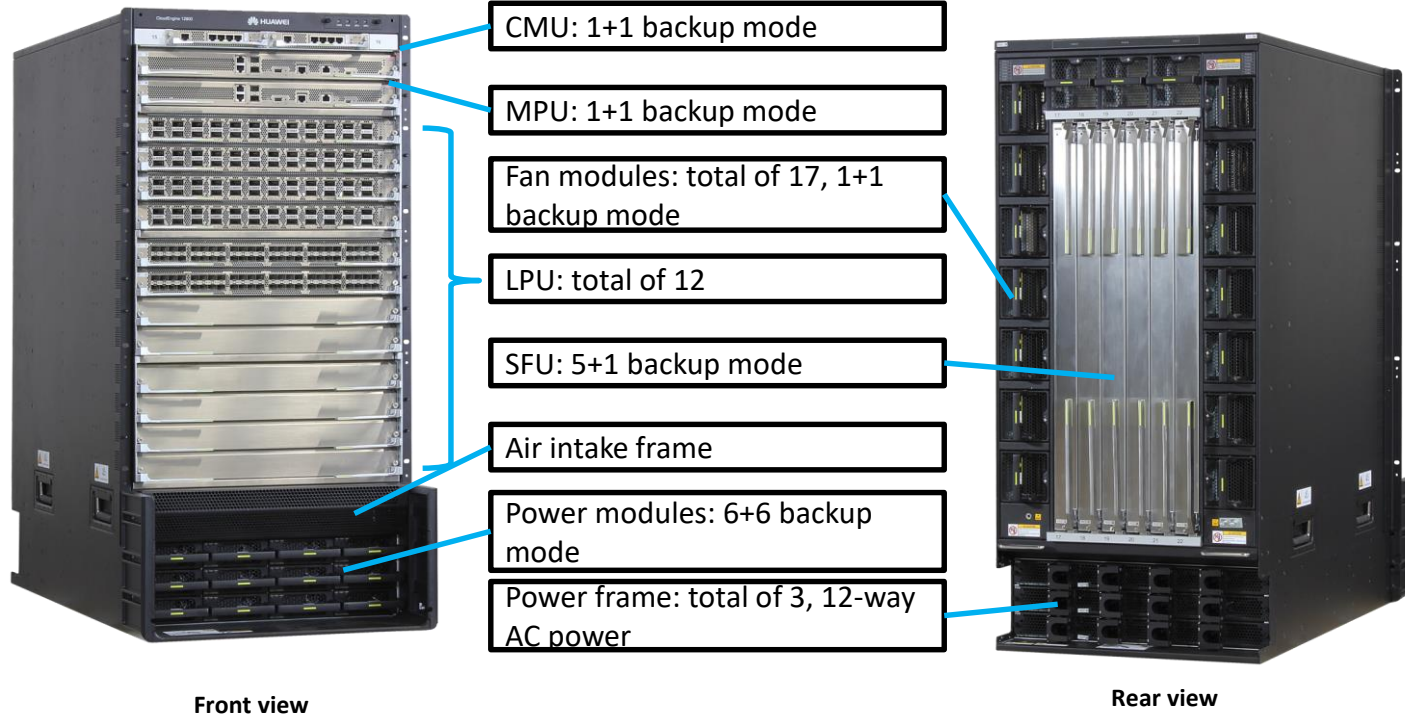


- Core Routers **Evolution**
- **SDN/NFV** Evolution
- Router **Simulation**
- **K Labs** Job opportunities
- K Labs **Internship**





JUNIPER
NETWORKS®



Scalable System Platform



High-speed Interconnection

Large Capacity Powering/Heat Dissipation

Highly Integrative Chip

High-density Optical Module

Unblock Switching



Dynamic CLOS Switching

VSC Exchange

Distributed Arbitration

Dynamically Distributed Buffer

Energy-Saving



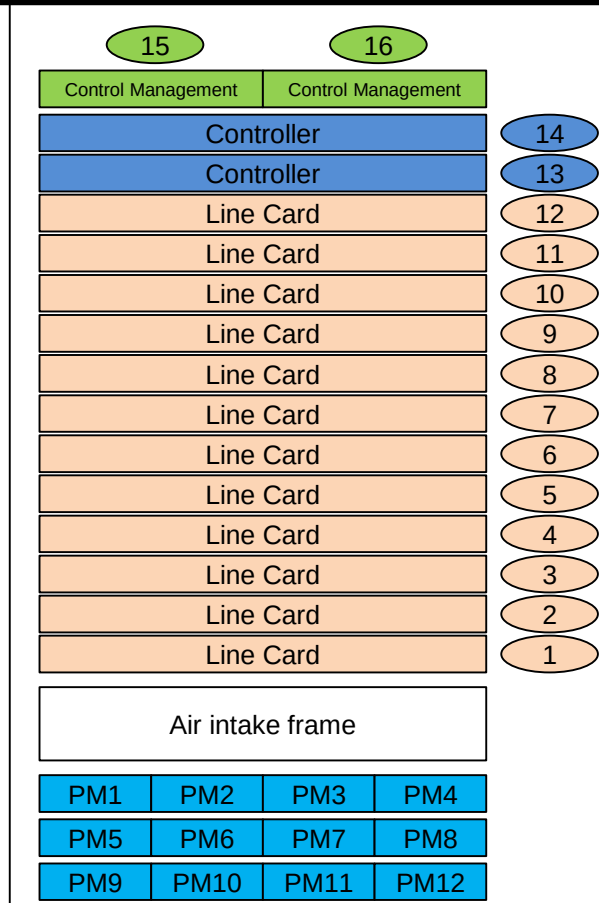
Patented Heat Dissipation Design: Orthogonal Front-to-rear Air Channels

Separated Air Channels on Service Slots and Switching Fabric Units

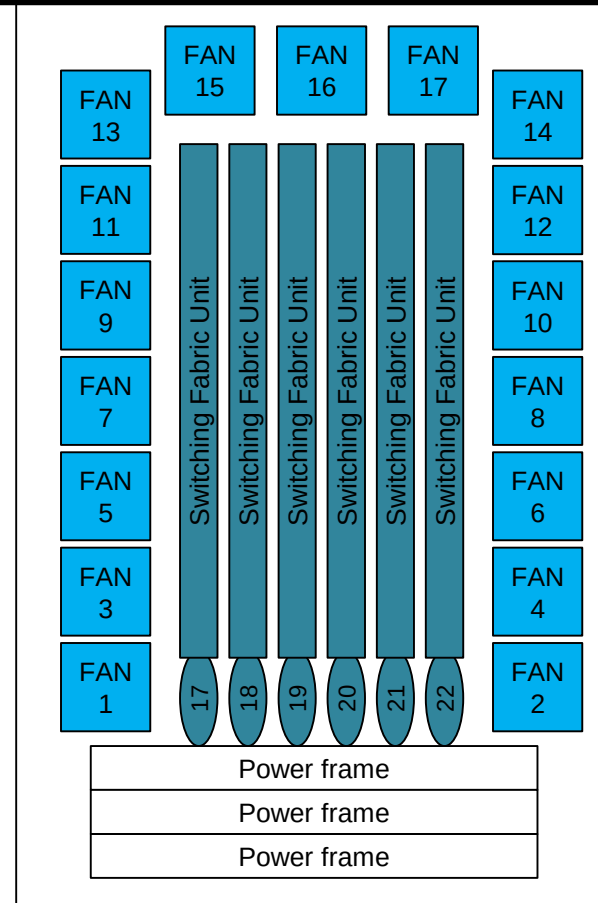
Innovative Panel Heat Dissipation Design

On-demand Powering/Dynamic Energy-saving

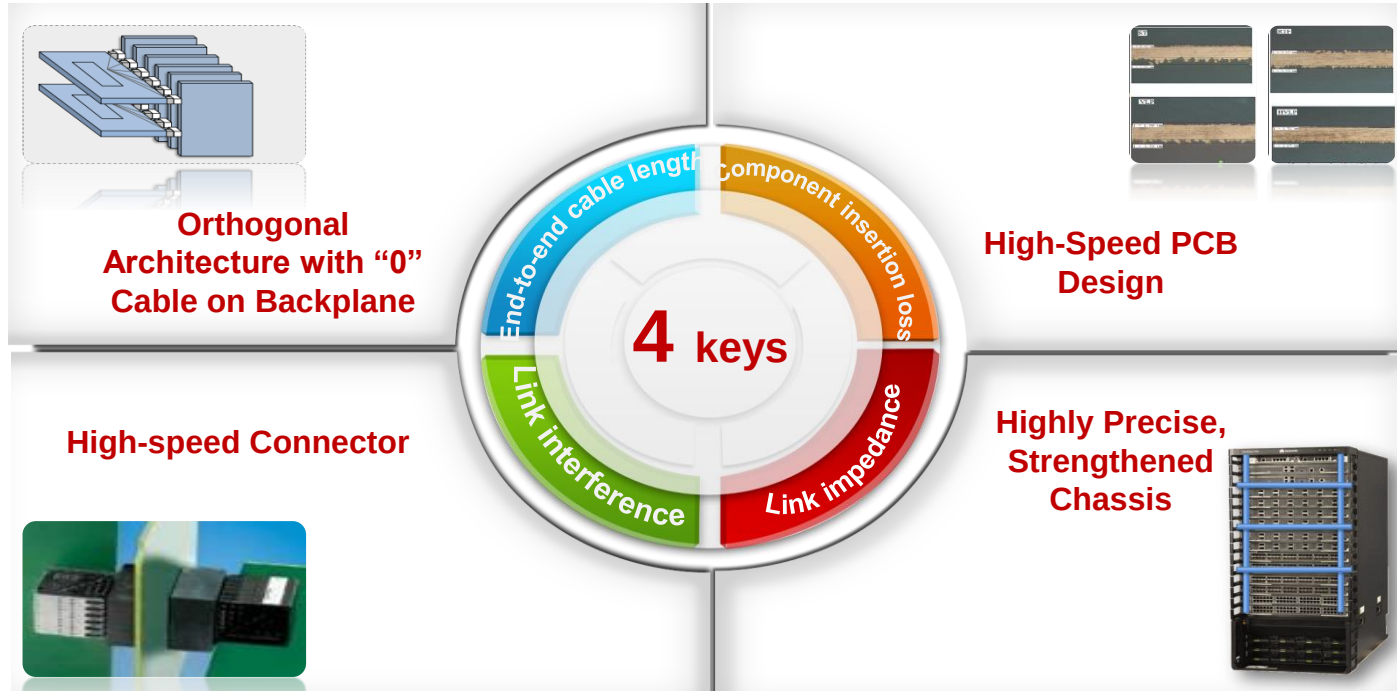
Slot Distribution Diagram example



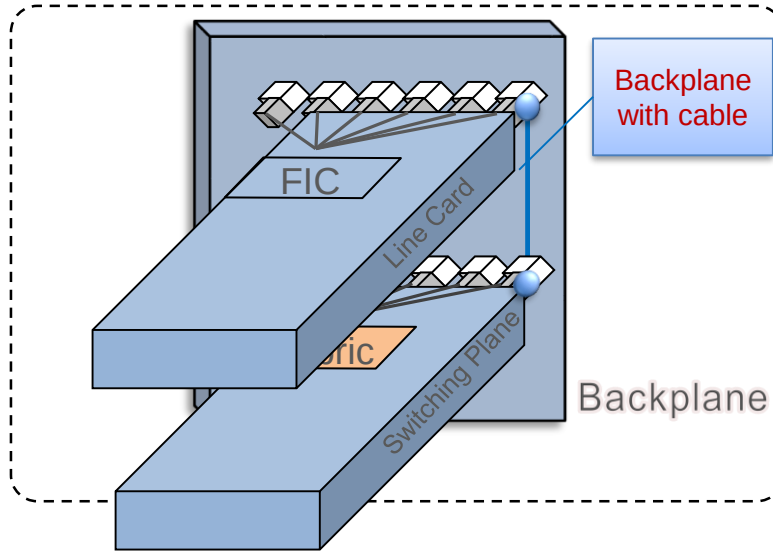
front view



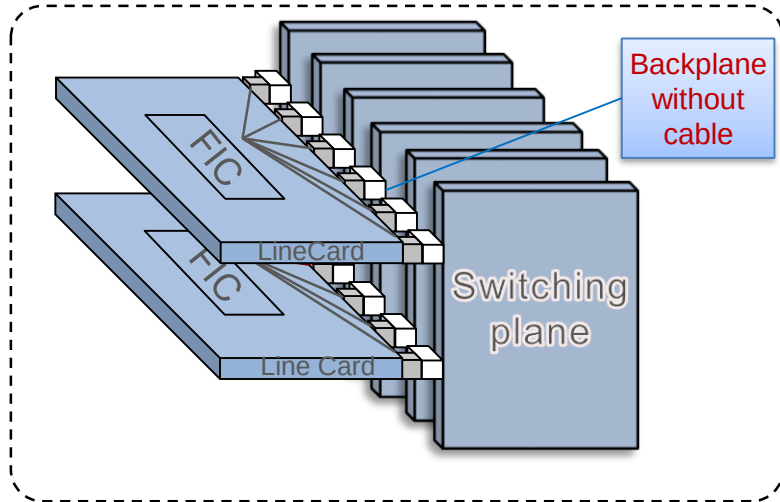
rear view



• Ensuring high performance of end-to-end high-speed links •



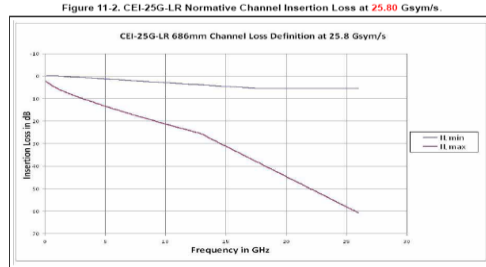
Traditional switching architecture



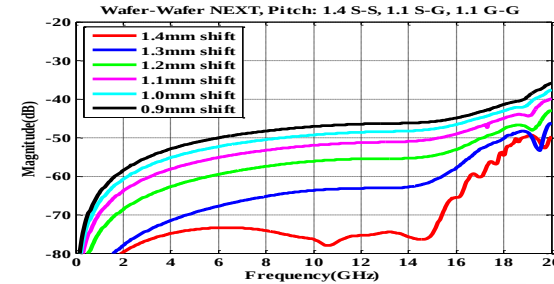
Fully orthogonal architecture

Fully orthogonal design of line cards and Switching Fabric Units

- On a core router, the cables from line cards to Switching Fabric Units are the most important factor affecting slot bandwidth.
- In the traditional architecture, the length and rate of backplane link are the important factors affecting device bandwidth and evolution capability.
- The orthogonal architecture, **reducing the backplane cable length to 0** and improve system bandwidth and evolution capability.

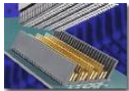


Insertion loss



Interference

2000



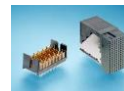
1.25-3.125G

2004



3.125-6.25G

2008



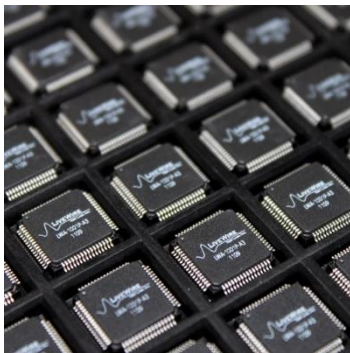
6.25-10.3G

2012



10.3-25G

High-speed connector is the basis of core switch
Next-generation core routers use a minimum of 10.3G links, which can be upgraded to 25G

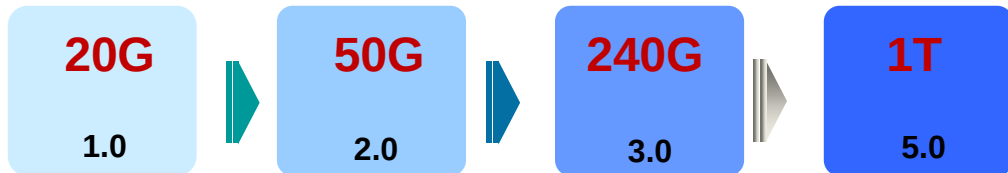


ASIC

VS

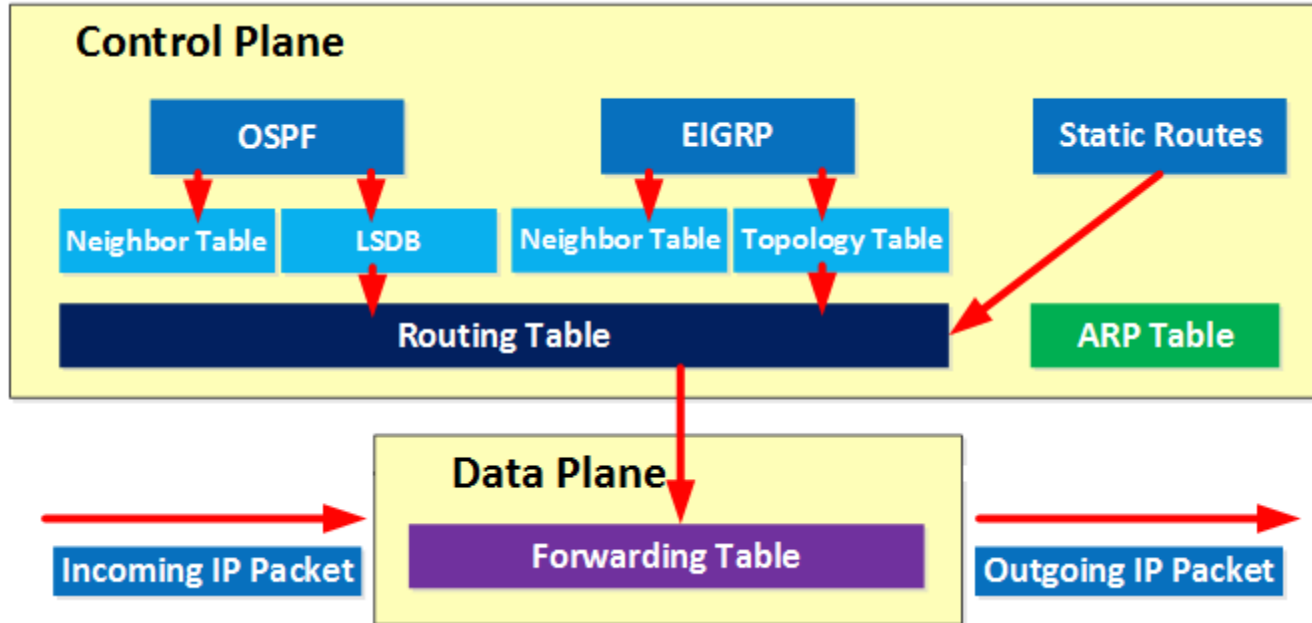


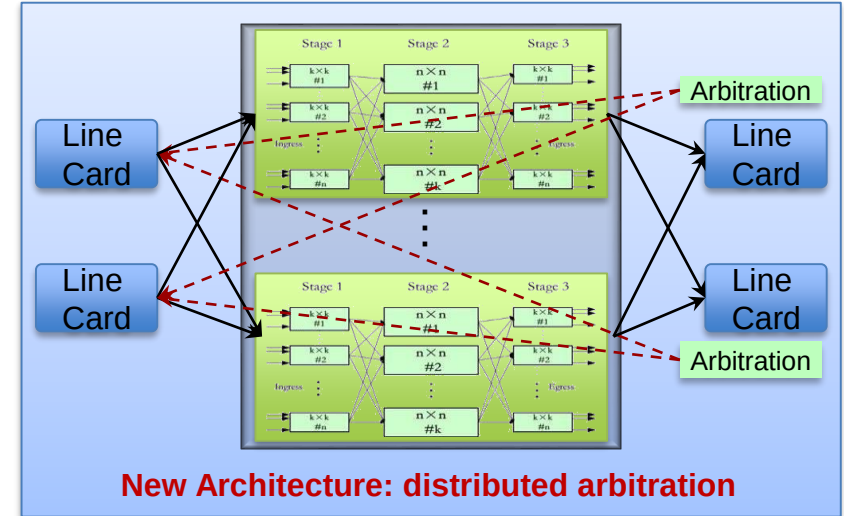
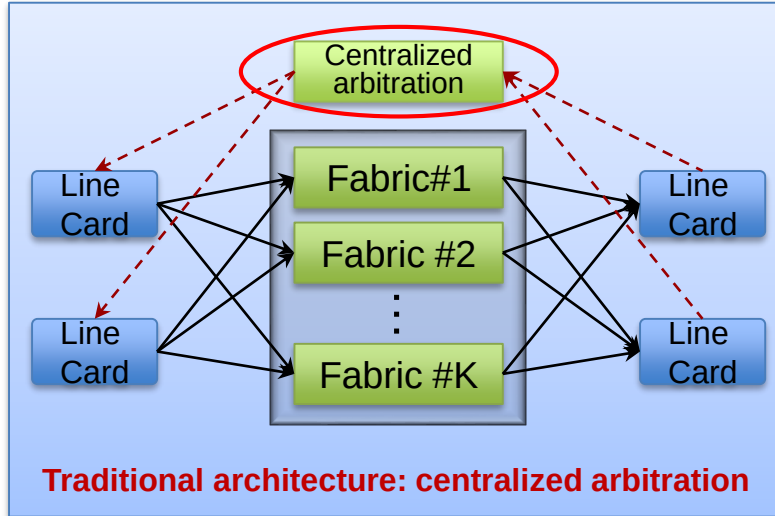
General Purpose CPU



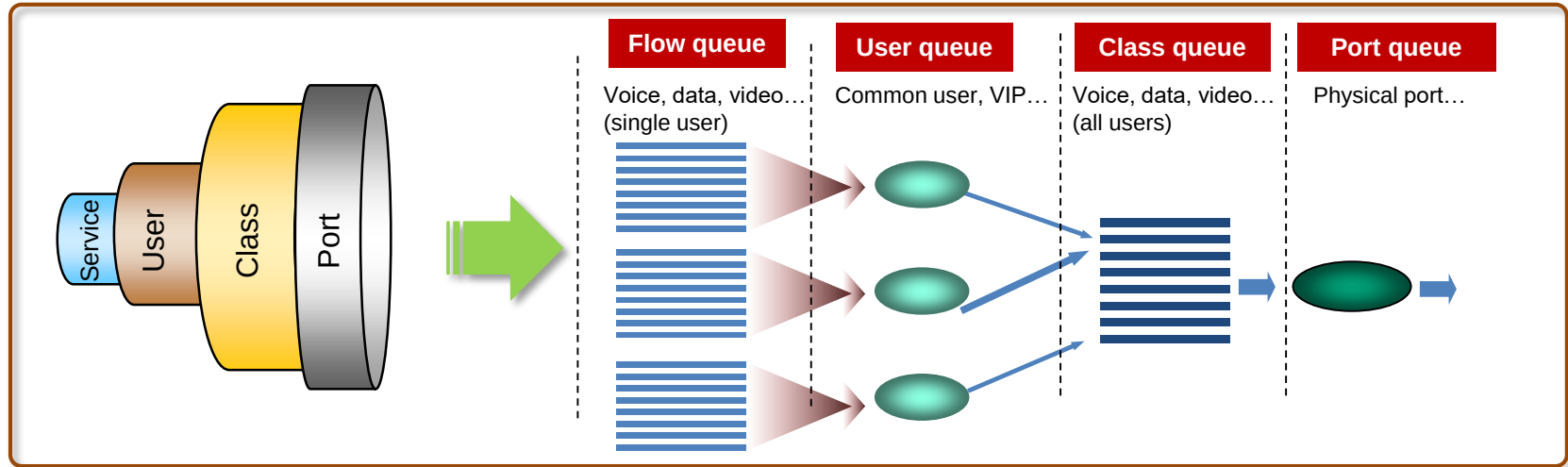
ASIC Chipset Evolution

Control Plane and Data Plane Separation 2/2





Distributed arbitration improves scalability of the switching network



Traditional QoS

- **Per port bandwidth control:** service traffic is differentiated based on classes of service but not users
- **Unable to manage and schedule multiple services of multiple users**

H-QoS

- **Hierarchical per-user-per-service scheduling,** quality guarantee for VIP users and high-priority services
- **High performance**



36*100GE QSFP28



36*40GE QSFP+



**48*10GE SPF+ +
2*40GE+2*100GE**

10GE Flex Port



SFP-T: RJ45,
GE electrical



100m

SFP: GE optical
port connection



500m,
10Km, 40km,
80km, 100km

10GE AOC:
Short-distance, low-
cost connection



3m, 10m, 20m

10Gecopper cable:
Low-cost connection
within 5m



1m, 3m, 5m,
7m, 10m

SFP+: 10GE optical
port connection



100m, 220m, 300m,
1.4km, 10km,
40km, 80km

40GE Flex Port



QSFP+ connection



100m, 150m, 300m,
400m, 1.4km, 10km,
40km

40GE copper cable:
Low-cost connection
within 5m



1m, 3m, 5m

40GE AOC:
Short-distance, low-
cost connection



10m

One 40GE splits into 4*10GE

**Fiber
connection**



300m, 1.4km, 10km

**Copper cable
connection**



1m, 3m, 5m

AOC connection



10m

100GE Flex Port



CFP 100G fiber connection



100m,
10km, 20km,
40km, 80km



CXP 100G fiber connection



100m



CFP2 100G fiber connection



100m, 10km



QSFP28 100G fiber connection



100m, 500m
2km, 10km

100GE split into 2/3*40GE



100m

Cable connection



10m

100GE split into 8/10/12*10GE



100m

100GE split into 4*25GE



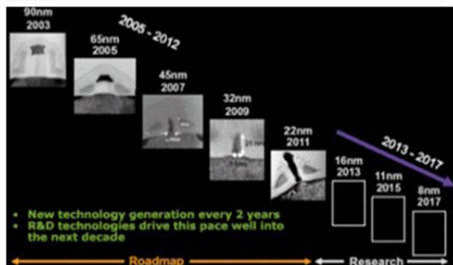
100m, 500m



1m,
3m, 5m

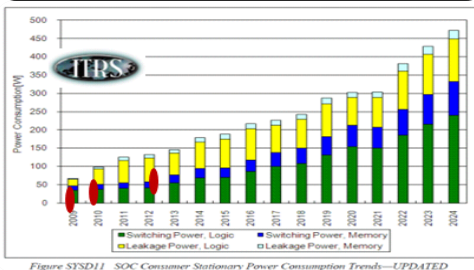
Large Capacity Powering/Heat Dissipation

Chip techniques upgrade every two years

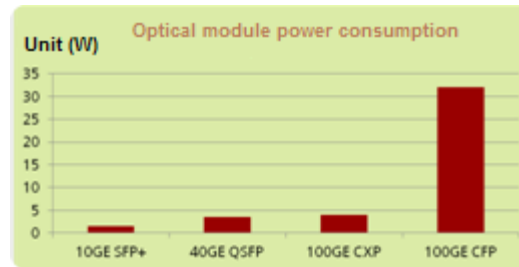


A highly integrative chip has high power consumption. In 2012, the power consumption of a single chip exceeds 100 W.

Power consumption of a single chip exceeds 100W



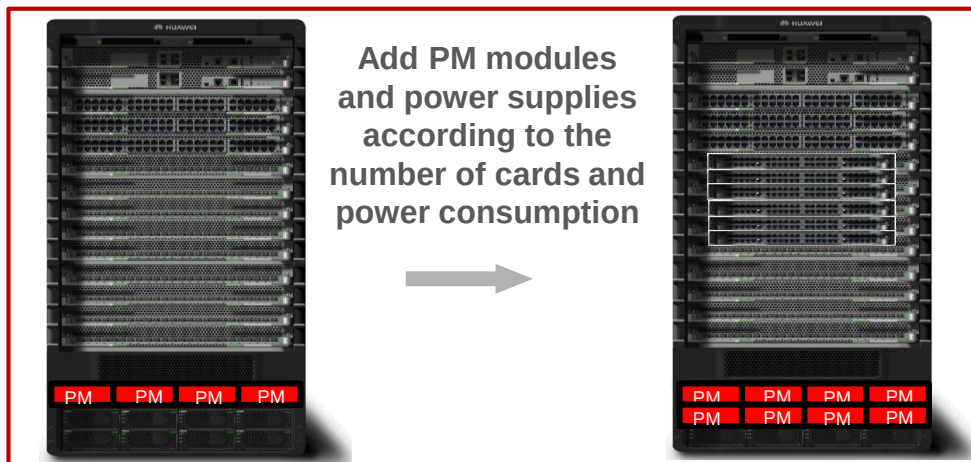
Power consumption of optical module greatly increases



The optical module is migrating to 100GE, with increasing power consumption.

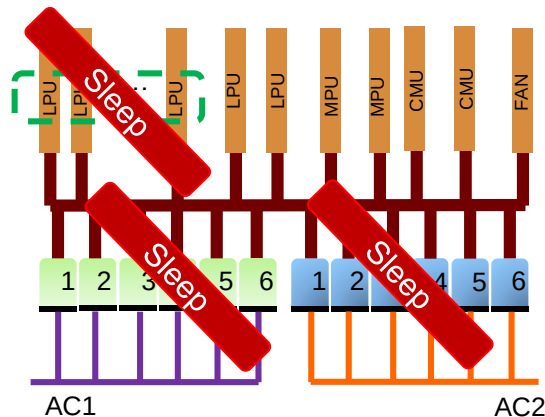
Increasing power consumption of chip and optical module poses high requirements on core devices:
System powering capability---20KW for the chassis
System heat dissipation---heat dissipation per slot exceeds 1000W

On-demand Powering/Dynamic Energy-Saving



On-demand power configuration

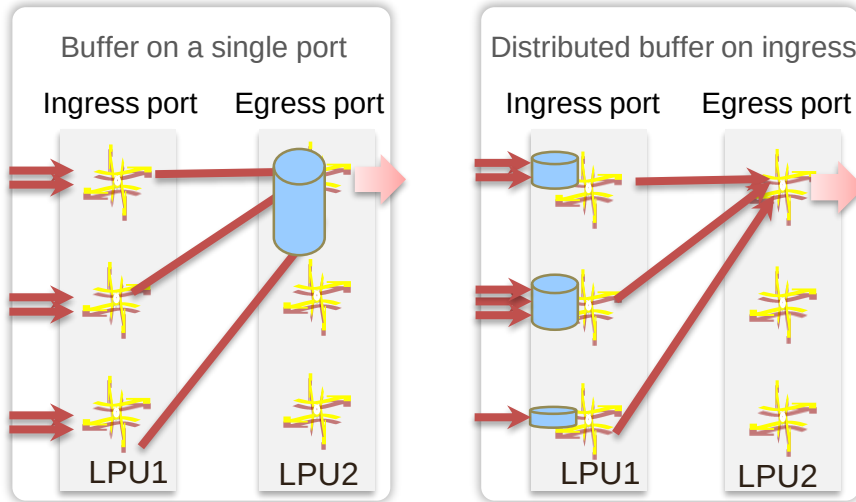
- Restrict the number of initially configured power modules, controlling initial investment
- Power module control based on small granularities, expanded on demand



Improve power efficiency, reduce conversion loss

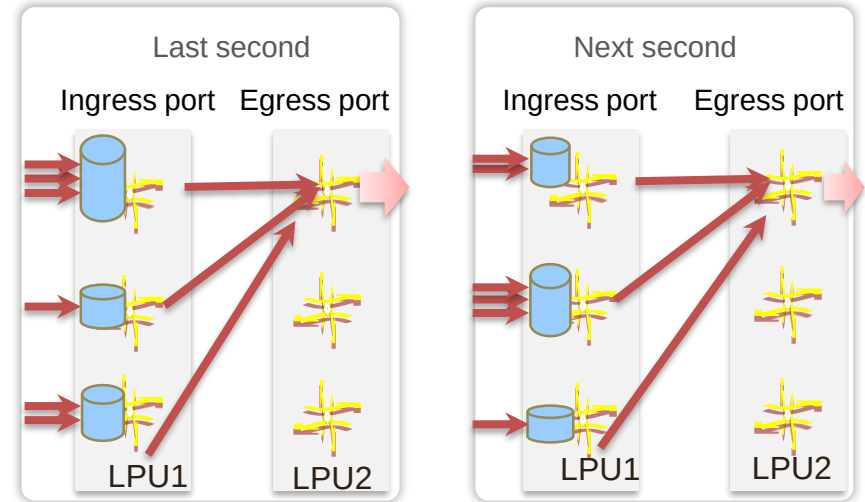
- Accurate power configuration implements 80% power loading and increases power use efficiency to **96%**.

Distributed buffer can accommodate burst traffic



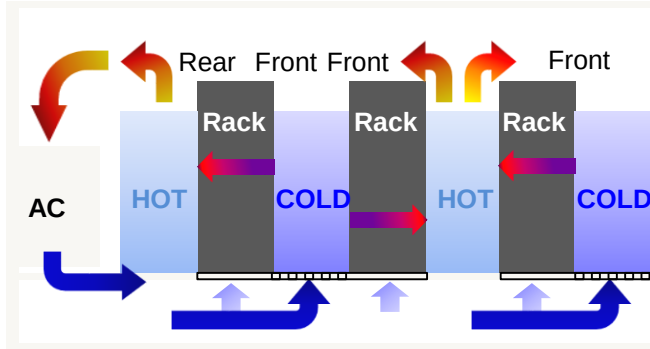
- Distributed buffer on ingress eases buffer loads on a single port •

Dynamic buffer improves buffer use efficiency



- Buffer is allocated on demand and dynamically adjusted •

→ Data flow  Buffer



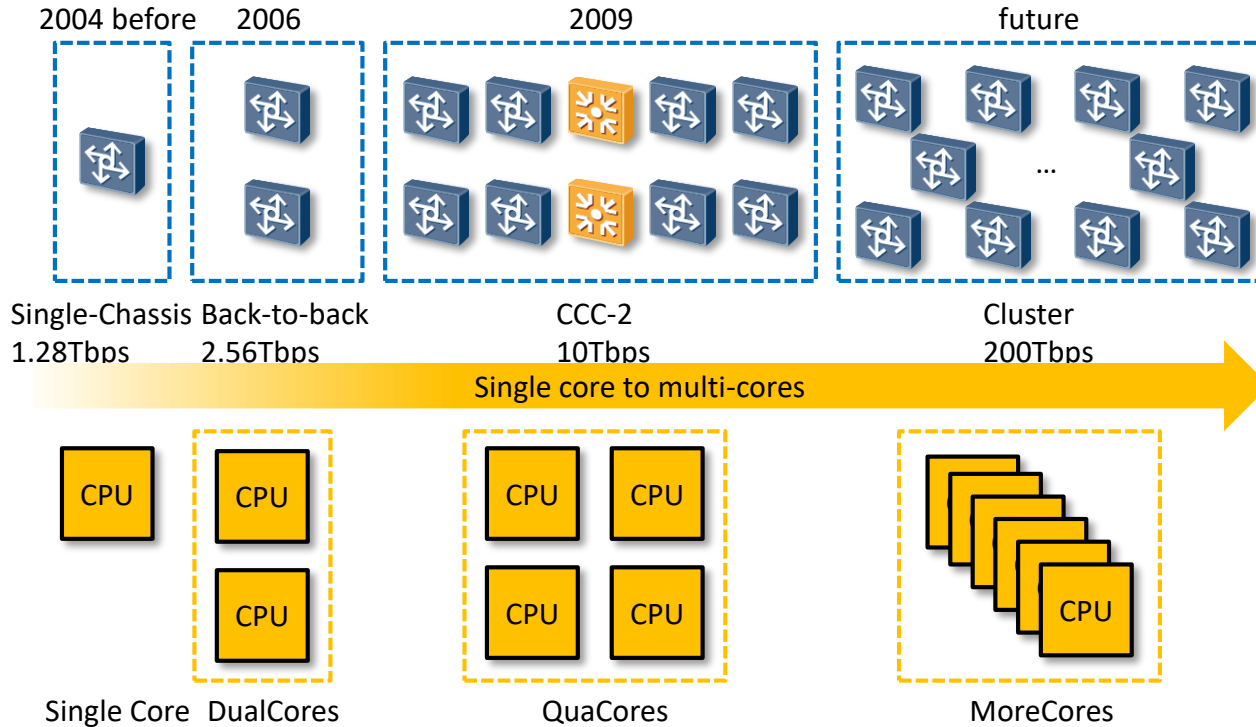
Typical air channel in Data Center Room

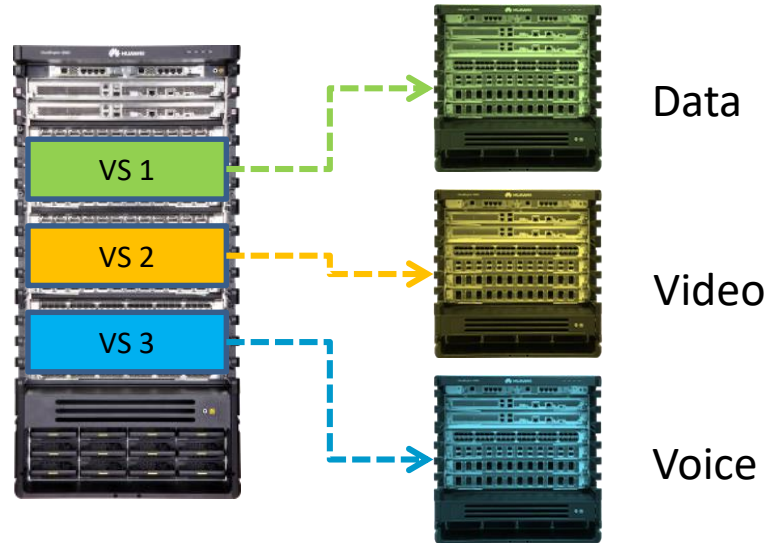
- The cabinets are placed in the “**face-to-face, back-to-back**” manner, separating the cold and hot air channels.
- After flowing into the cabinet and chassis through the bottom of the cabinets, cold air becomes the hot air, flows into the hot air channel, and flows back through the return air channel.

Trend: front-to-rear, complying with standards

- ANSI TIA-92
- NEBS GR-63-CORE
- If the chassis does not comply with standard, increase **10°C** to perform test in high temperature.
- Data center devices must provide the front-to-rear air channels.

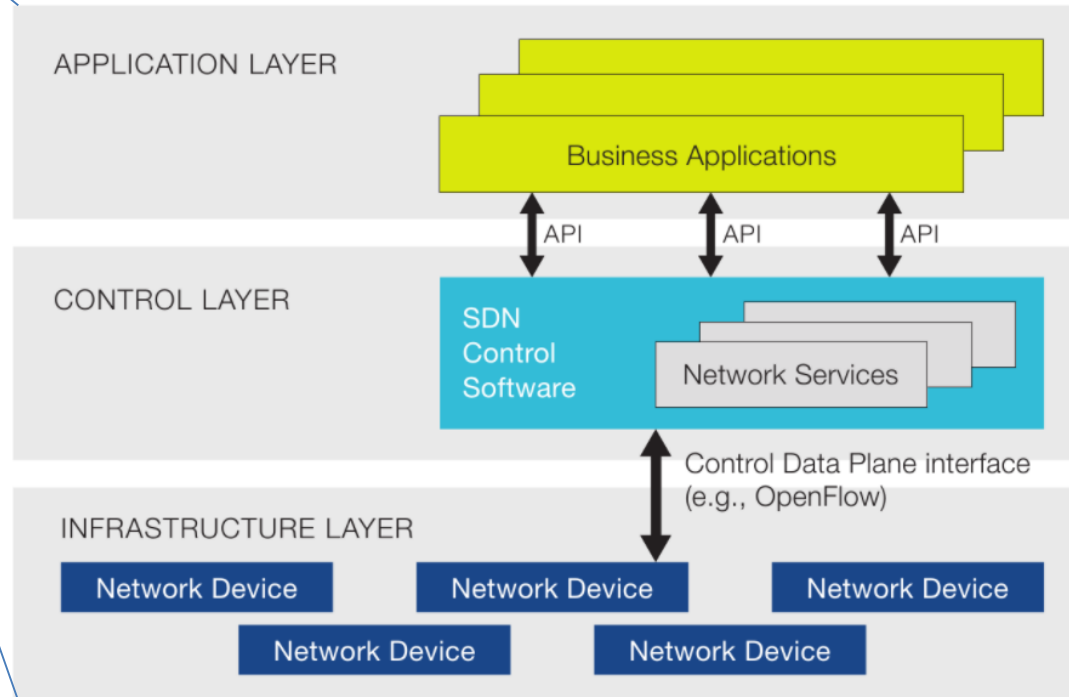
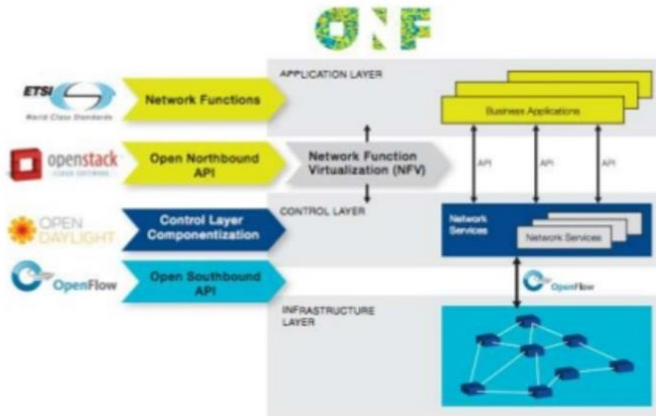
Hardware and operating system evolution



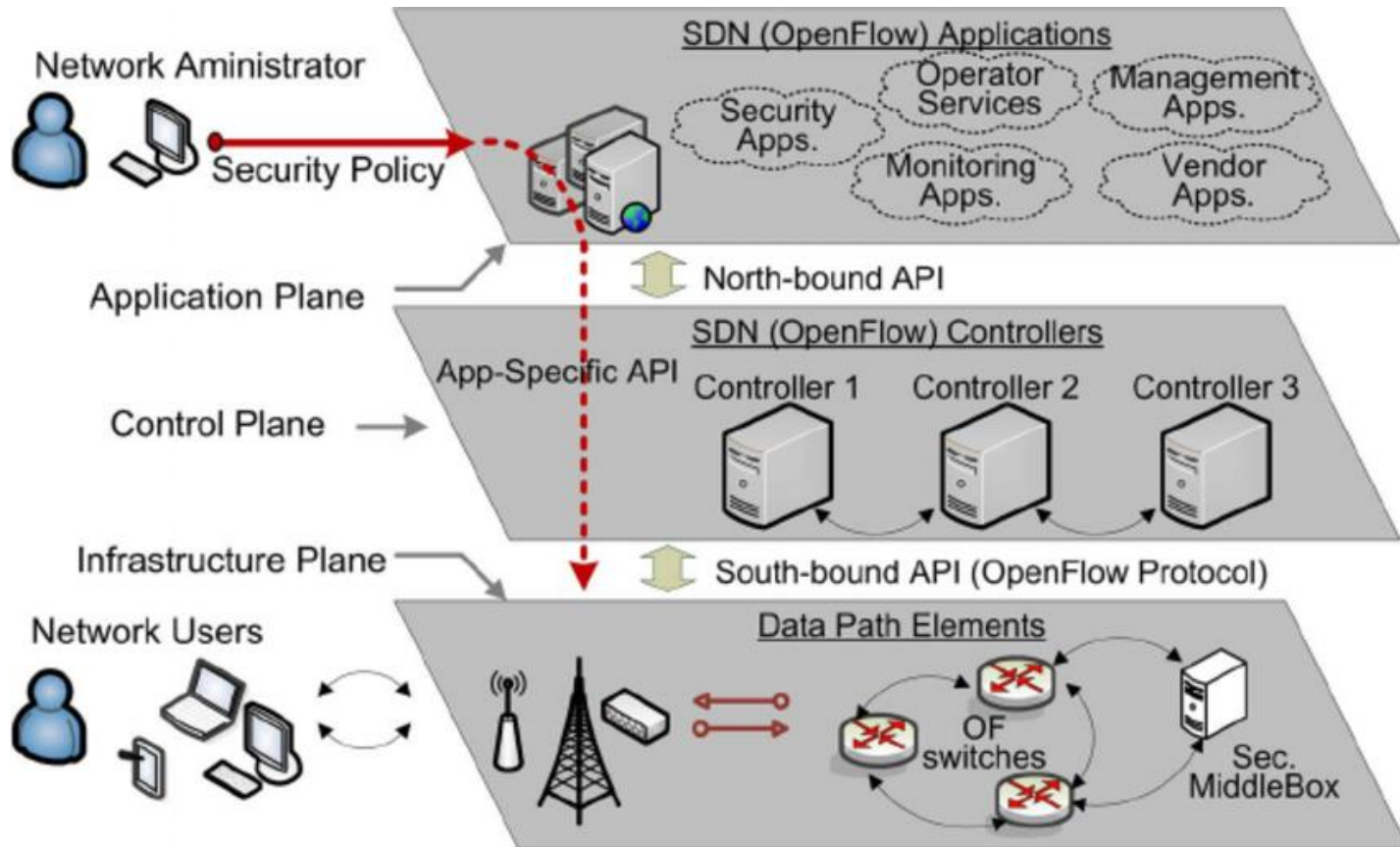


VS technology can make the handling capacity of a single physical router powerful fully utilized and simplify network, simplify management, strengthen the safety and reliability

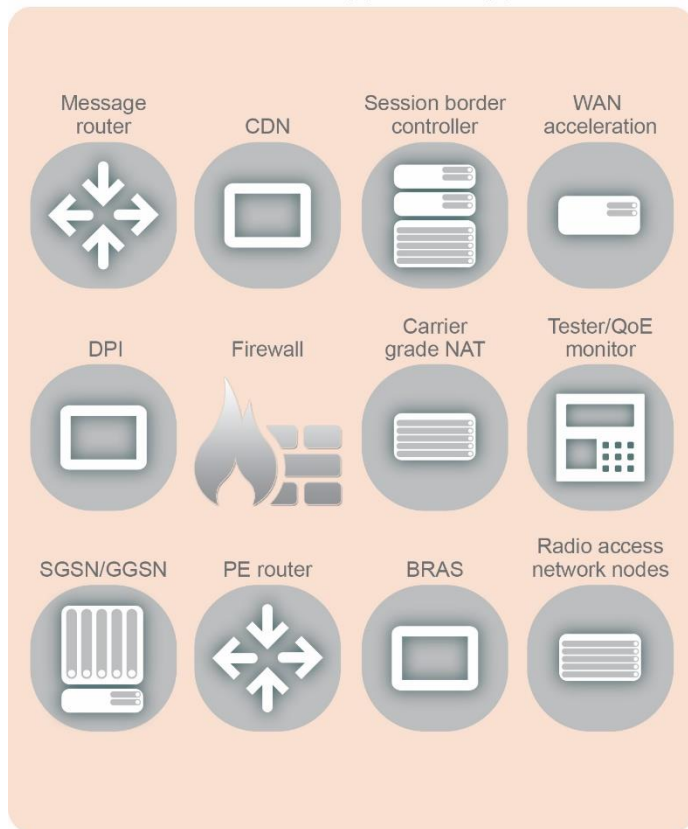
Software Defined Networking (SDN)



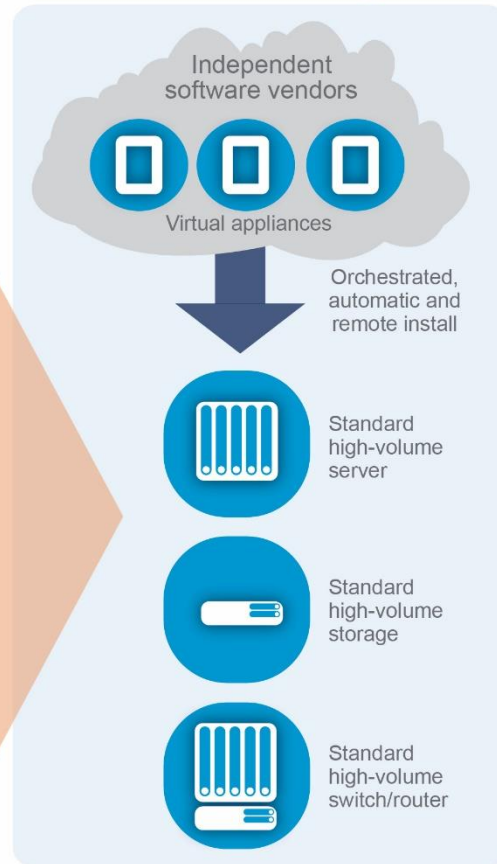
Network Processor for SDN Scenario

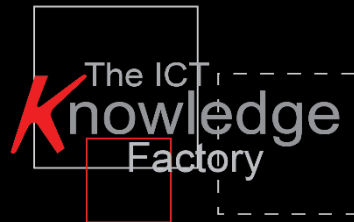


Classic Network Appliance Approach

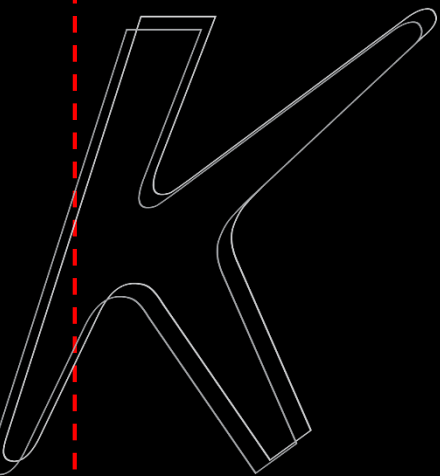


Network Virtualization Approach





K Labs Company Presentation



K Labs is a company
specialized in
Technical Trainings
for
Telco and **ICT** market



ISO 9001:2008
Certified





Our aim is to deliver **vendor-independent**, **high-quality** training courses that provide delegates with **real-life experience** on software and hardware in addition to imparting **theoretical knowledge**. As such, our courses include plenty of practical **hands-on** time.





- DATA CENTER



- CLOUD COMPUTING



- IP NETWORKING



- ICT SECURITY



- CARRIER



- FIXED ACCESS



- LTE



- MOBILE NETWORKS



- MULTIMEDIA



- PERFORMANCE TESTING



- GREEN IT



- SOFTWARE

K Labs delivers training services to a lot of big players or companies involved in the Telecommunication and ICT Market.



K Labs signed training partnership with the most important Manufacturers in the ICT Global Market.

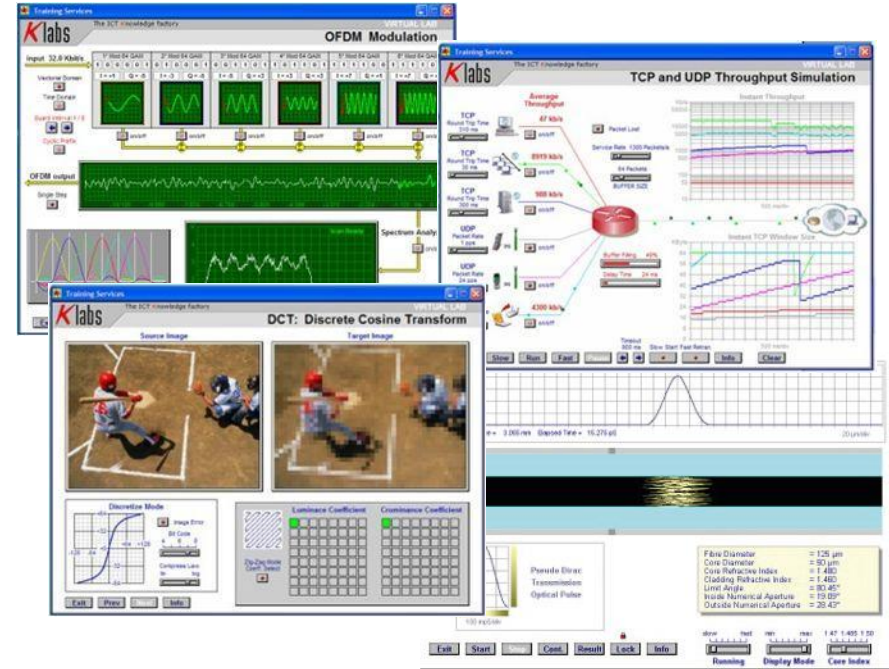


Educational Lab (Multivendor)

Virtual Lab (Software simulations)



Test Instruments



Do you enjoy the challenge of learning the newest technologies on the ICT market ?

Do you have a pioneering spirit and enjoy being seen a subject matter expert ?

K Labs want to invest in bright and dynamic Engineers that would like to join our team of enthusiastic and highly qualified: **“Trainer and Professional Engineer”**

For more information on Internships and Job positions:

Tel. 059 821229, e-mail: job@klabs.it www.klabs.it



Requirements for the applicants



2nd or 3rd year of Telecommunications,
Computer Science or Electronics preferred

Passion for technology and
telecommunications

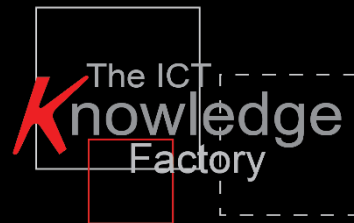
Good communication skills

Good knowledge of English

Flexibility and Adaptability to change

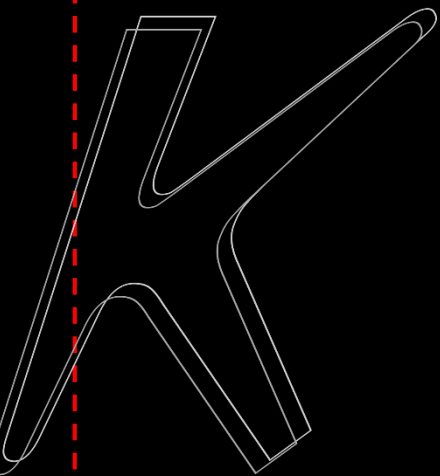
Optimism, Proactivity

The candidates will be interviewed before being admitted to the internship



K Labs Internship

**an opportunity to jump
into the ICT world**





Software Defined Networking



Internet of Things



Mobile 5G

Internship 1: Software Defined Networking



Field: Software Defined Networking

Description: Preliminary study and development of a test environment able to check multivendor devices interworking controlled by SDN.

Test Environment Design, SDN Function Evaluation, Test Execution, Reporting.

Team work in cooperation with K Labs engineers.

Application Deadline: Available Year-round

Internship 2: Internet of Things

Field: Internet of Things

Description: Preliminary study and development of a test environment able to check multivendor IoT devices interworking.

Test Environment Design, IoT Function Evaluation, Test Execution, Reporting

Team work in cooperation with K Labs engineers.

Application Deadline: Available Year-round



Field: 5G

Description: Preliminary study and content development of an e-learning training course focused on 5^o Generation Mobile Network and Services.

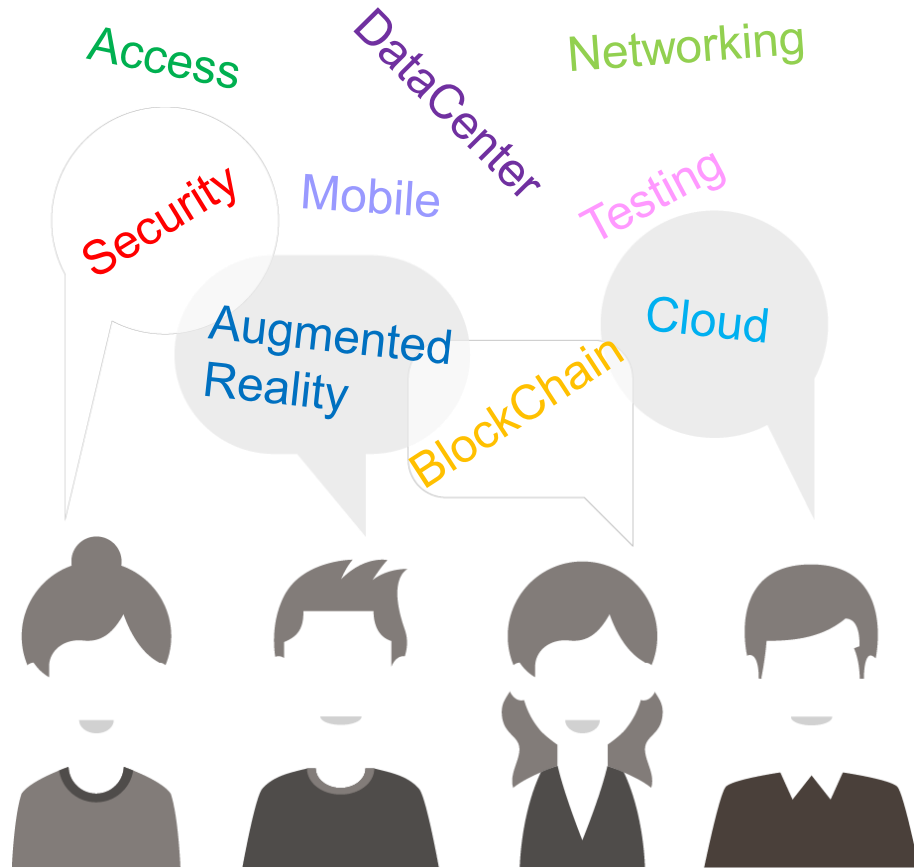
5G Standard evaluation, Learning Objects Design, cooperation with Multimedia Developer for e-learning course implementation.

Team work in cooperation with K Labs engineers.

Application Deadline: Available Year-round

Suggestions?

You can suggest us also different topics, in order to design together your internship @K Labs





Per maggiori informazioni:

Tel. 059 821229
e-mail: job@klabs.it
www.klabs.it

Klabs
The ICT **K**nowledge factory